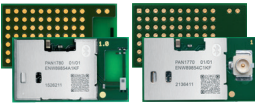
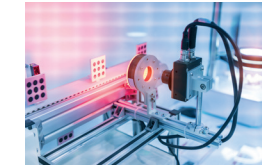


Wireless Connectivity

Product Leaflet

	Bluetooth® Low Energy	Bluetooth® LE & IEEE® 802.15.4			
					
SERIES	PAN1740A	PAN1780 / PAN1770	PAN1781	PAN1782	PAN1783(A)
STATUS	Mass Production	Mass Production	Mass Production	Mass Production	In Development
PART NUMBER	ENW89852A1KF	ENW89854A1KF (PAN1780) ENW89854A3KF (PAN1780AT) ENW89854C1KF (PAN1770) ENW89854C2KF (PAN1770 APP)	ENW89857A1KF	ENW89858A1KF	ENW89860A1KF (Chip Antenna) ENW89860C1KF (Bottom Pad)
RF CATEGORY	Bluetooth® 5.0	Bluetooth® 5.3, IEEE® 802.15.4 & NFC-A	Bluetooth® 5.3, IEEE® 802.15.4	Bluetooth® 5.3, IEEE® 802.15.4 & NFC-A	Bluetooth® 5.3, IEEE® 802.15.4 & NFC-A
SOFTWARE & DRIVERS	SDK by Dialog	nRF Connect SDK	nRF Connect SDK	nRF Connect SDK	nRF Connect SDK
INTEGRATED CIRCUIT	DA14585	nRF52840	nRF52820	nRF52833	nRF5340
SIZE [MM]	9.0 x 9.5 x 1.8	15.6 x 8.7 x 2.0	15.6 x 8.7 x 2.0	15.6 x 8.7 x 2.0	15.6 x 8.7 x 2.0
RX SENSITIVITY [DBM]	-93 @ 1Mb/s	-95 @ 1Mb/s -103 @ 125kb/s	-95 @ 1Mb/s -103 @ 125kb/s	-96 @ 1Mb/s -103 @ 125kb/s	-97 @ 1Mb/s -103 @ 125kb/s
TX POWER (MAX.) [DBM]	+0	+8 (Chip Antenna)	+8	+8	+3 (Chip Antenna)
POWER SUPPLY [V]	2.2 to 3.3	1.7 to 5.5	1.7 to 5.5	1.7 to 5.5	1.7 to 5.5
CURRENT CONSUMPTION	Tx: 4.9mA, 3V @ 0dBm Rx: 4.9mA, 3V	Tx: 4.8mA, 3.3V @ 0dBm Rx: 4.8mA, 3.3V	Tx: 4.9mA @ 0dBm Rx: 4.7mA	Tx: 4.9mA @ 0dBm Rx: 4.7mA	Tx: 3.4mA @ 0dBm Rx: 2.7mA
SLEEP MODE CURRENT	Sleep Mode (Full RAM Retention): 4µA Deep Sleep Mode: 520nA	Wake-on-RTC: 1.5µA Off Mode: 0.4µA	Wake-on-RTC: 1.2µA Off Mode: 0.3µA	Wake-on-RTC: 1.5µA Off Mode: 0.6µA	Wake-on-RTC: 1.5µA Off Mode: 0.9µA
INTERFACES	GPIO, UART, SPI+, I2C, ADC, 3-axis QD	GPIO, UART, QSPI, I2C, I2S, ADC, PDM, PWM, NFC-A, USB2.0	GPIO, UART, SPI, I2C, USB2.0, QDEC	GPIO, UART, QSPI, I2C, I2S, ADC, PDM, PWM, COMP, USB2.0	GPIO, UART, QSPI, I2C, I2S, ADC, PDM, NFC-A, USB2.0
MICROCONTROLLERS AND MEMORY	ARM® Cortex®-M0 96kB SRAM, 64kB OTP	ARM® Cortex®-M4F 256kB RAM, 1MB Flash	ARM® Cortex®-M4 32kB RAM, 256kB Flash	ARM® Cortex®-M4 128kB RAM, 512kB Flash	Dual ARM® Cortex®-M33 512kB RAM, 1MB Flash 64kB RAM, 256kB Flash
OPERATING TEMP. [°C]	-40 to +85	-40 to +85	-40 to +85	-40 to +85	-40 to +85
EVALUATION KIT	ENW89852AXKF (Dongle) ENW89852AWKF (Dongle Kit)	ENW89854AJKF (PAN1780 EVB) ENW89854AVKF (PAN1780AT EVB) ENW89854CXKF (PAN1770 EVB) ENW89854CZKF (PAN1770APP EVB)	ENW89857AXKF (Board)	ENW89858AXKF (Board)	ENW89860AXKF (Board)

Applications



Industrial IoT



Smart Home/Building



Beacons



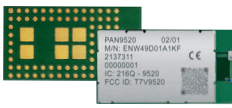
Medical Devices

Status of engineering sample (ES) are expected as of the time of leaflet production.
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Panasonic Industry Europe GmbH
wireless.connectivity@eu.panasonic.com
<https://industry.panasonic.eu>

Wireless Connectivity

Product Leaflet

SERIES	Bluetooth® Dual Mode	Wi-Fi® & Bluetooth® LE			Wi-Fi®
					
STATUS	PAN13x6C/2	PAN9026	PAN9028	PAN9019(A)	PAN9520
PART NUMBER	Mass Production	Mass Production	Mass Production	In Development	Mass Production
RF CATEGORY	ENW89823A5KF (Chip Antenna) ENW89823C4KF (Bottom Pad)	ENWF9202A1EF (EU) ENWF9201A1EF (US) ENWF9203A1EF (CA) ENWF9208A1EF (Multi-region)	ENWF9408A1EF (with PMIC) ENWF9408A2EF (without PMIC)	ENWF9501C1KF (PAN9019) ENWF9511C1KF (PAN9019A)	ENW49D01A1KF (4 MB Flash / 2 MB RAM) ENW49D02A1KF (1 MB Flash / No RAM)
SOFTWARE & DRIVERS	Bluetooth® 5.1 Dual Mode (BR, EDR, Bluetooth® LE)	Wi-Fi® 4 Radio 2.4 GHz & 5.0 GHz 802.11 a/b/g/n & Bluetooth® 5.0 (BR, EDR, LE)	Wi-Fi® 5 Radio 2.4 GHz & 5.0 GHz 802.11 a/b/g/n/ac & Bluetooth® 5.2 (BR, EDR, LE)	Wi-Fi® 6 Radio 2.4 GHz & 5.0 GHz 802.11 a/b/g/n/ac/ax & Bluetooth® 5.2 (BR, EDR, LE) only PAN9019A: & 802.15.4	Wi-Fi® 4 Embedded 802.11 b/g/n
INTEGRATED CIRCUIT	CC2564C	Linux & i.MX RT Support	Linux, Android, i.MX RT Support	Linux, Android, i.MX RT Support	ESP-IDF by Espressif Arduino IDE
SIZE [MM]	9.0 x 9.5 x 1.8 (with Antenna) 9.0 x 6.5 x 1.8 (no Antenna)	88W8977	88W8987	IW611 (PAN9019) IW612 (PAN9019A)	ESP32-S2
RX SENSITIVITY [DBM]	-90	17.5 x 10.0 x 2.6	24.0 x 12.0 x 2.8	15.3 x 12.0 x 2.5	24.0 x 13.0 x 3.1
TX POWER (MAX.) [DBM]	+10 (Chip Antenna) +11.5 (no Antenna)	-98 @ 1M-DSSS	-98 @ 1M-DSSS	-98 dBm @ 1M 802.11b	-97 @ IEEE 802.11b
POWER SUPPLY [V]	1.7 to 4.8	+17 @ IEEE 802.11b	+16 @ IEEE 802.11b	+17 @ IEEE 802.11ax	+19.8 @ IEEE 802.11b
CURRENT CONSUMPTION	1.7 to 4.8	1.8 to 3.3	3.3 with PMIC 1.1, 1.8, 2.2, 3.3 without PMIC	1.8V and 3.3V	3.0 to 3.6
SLEEP MODE CURRENT	Tx: 40mA, 3.3V @ 8dBm Rx: 20mA, 3.3V	Tx: 400mA @ 11Mb/s Rx: 70mA @ 11Mb/s	Tx: 320mA @ 11Mb/s Rx: 60mA @ 11Mb/s	Tx: 192mA @ 802.11ax, 5GHz Rx: 180mA @ 802.11ax, 5GHz	Tx: 190mA, 3.3V @ 19.5 dBm Rx: 63mA, 3.3V @ 1 Mb/s
INTERFACES	Deep Sleep Mode: 105 µA	Power Down Mode: 150µA	Power Down Mode: 150µA	Power Down Mode: 190uA	Deep sleep mode <100 µA
MICROCONTROLLERS AND MEMORY	GPIO, UART, PCM	SDIO 3.0, HS UART, PCM	GPIO, SDIO 3.0, HS UART, PCM	SDIO 3.0, HS UART, SPI	GPIO, UART, SPI, I2C, I2S, RMT, PWM, USB, LCD, ADC & DAC
OPERATING TEMP. [°C]	Xtensa® 32-bit LX7 320 kB SRAM, 128 kB ROM internal memory Integrated QSPI Flash and PSRAM (size depending on version)	-40 to +85	-30 to +85	-30 to +85	-40 to +85
EVALUATION KIT	ENW89819AYKF (EMK without Antenna)	ENWF9201AWEF (mSDIO Dongle) ENWF9201AYEF (SDIO Dongle Kit) ENWF9201AXEF (i.MX Kit)	ENWF9408AVEF (mSD Adapter) ENWF9408AMEF (M.2 EVB)	ENWF9501CMKF (PAN9019 M2E EVD) ENWF9511CMKF (PAN9019A M2E EVD)	ENW49D01AZKF (Board with 4 MB Flash, 2 MB RAM)

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- > Different software/profile options available.

Panasonic Industry Europe GmbH
wireless.connectivity@eu.panasonic.com
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